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Vishay Siliconix

P-Channel 12 V (D-S) MOSFET



Marking code: 03

PRODUCT SUMMARY					
V _{DS} (V)	-12				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5 \text{ V}$	0.035				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -2.5 \text{ V}$	0.045				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -1.8 \text{ V}$	0.059				
Q _g typ. (nC)	9				
I _D (A) ^a	-5.1				
Configuration	Single				

FEATURES

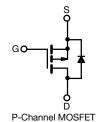
- TrenchFET® power MOSFET
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- · Load switch
- PA switch



ORDERING INFORMATION				
Package	SOT-23 (TO-236)			
Lead (Pb)-free	Si2333CDS-T1-E3			
Lead (Pb)-free and halogen-free	Si2333CDS-T1-GE3			

ABSOLUTE MAXIMUM RATING	iS (T _A = 25 °C, u	nless otherv	wise noted)	
PARAMETER		SYMBOL	LIMIT	UNIT
Drain-source voltage		V _{DS}	-12	V
Gate-source voltage		V_{GS}	± 8	V
	T _C = 25 °C		-7.1	
Continuous drain surrent /T 150 °C)	T _C = 70 °C	1 .	-5.7	
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	-5.1 ^{b, c}	
	T _A = 70 °C	İ	-4.0 b, c	А
Pulsed drain current		I _{DM}	-20	
Continuous source during displacement	T _C = 25 °C		-1.0	
Continuous source-drain diode current	T _A = 25 °C	I _S	-0.63 b, c	
	T _C = 25 °C		2.5	
NAC to a constant attack	T _C = 70 °C	1 5	1.6	147
Maximum power dissipation	T _A = 25 °C	P _D	1.25 ^{b, c}	W
	T _A = 70 °C		0.8 ^{b, c}	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b, d	t ≤ 5 s	R _{thJA}	75	100	°C/W	
Maximum junction-to-case (drain)	Steady state	R_{thJC}	40	50] C/W	

Notes

- a. $T_C = 25$ °C
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 5 s
- d. Maximum under steady state conditions is 166 °C/W

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PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	-12	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	1 - 250	-	-13	-	m\//°C	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = -250 μA	-	2.6	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \mu A$	-0.4	-	-1	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$	-	-	± 100	nA	
Zana mata walta na alumin awamat		V _{DS} = -12 V, V _{GS} = 0 V	-	-	-1		
Zero gate voltage drain current	I _{DSS}	V _{DS} = -12 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-10	μA	
On-state drain current ^a	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	-20	-	-	Α	
		$V_{GS} = -4.5 \text{ V}, I_D = -5.1 \text{ A}$	-	0.0285	0.035		
Drain-source on-state resistance ^a	R _{DS(on)}	$V_{GS} = -2.5 \text{ V}, I_D = -4.5 \text{ A}$	-	0.036	0.045	Ω	
		V _{GS} = -1.8 V, I _D = -2.0 A	-	0.046 0.059 18.5 - S 1225 - pF			
Forward transconductance a	9 _{fs}	$V_{DS} = -5 \text{ V}, I_{D} = -5.3 \text{ A}$	-	18.5	-	S	
Dynamic ^b				1	L		
Input capacitance	C _{iss}		-	1225	-		
Output capacitance	C _{oss}	$V_{DS} = -6 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	315	-	pF	
Reverse transfer capacitance	C _{rss}		-	260	-		
Total gate charge	0	$V_{DS} = -6 \text{ V}, V_{GS} = -4.5 \text{ V}, I_D = -5.1 \text{ A}$	-	15	25		
Total gate charge	Qg		-	9	15	nC	
Gate-source charge	Q_{gs}	V_{DS} = -6 V, V_{GS} = -2.5 V, I_D = -5.1 A	-	1.9	-	liC	
Gate-drain charge	Q_{gd}		-	3.8	-		
Gate resistance	R_g	f = 1 MHz	-	4	-	Ω	
Turn-on delay time	t _{d(on)}		-	13	20		
Rise time	t _r	V_{DD} = -6 V, R_L = 6 Ω , I_D = -1 A,	-	35	60	ns	
Turn-off delay time	t _{d(off)}	$V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$	-	45	70	113	
Fall time	t _f		-	12	20		
Drain-Source Body Diode Characteristi	cs						
Continuous source-drain diode current	I _S	$T_C = 25 ^{\circ}C$	-	-	-1	Α	
Pulse diode forward current ^a	I _{SM}		-	-	-20		
Body diode voltage	V_{SD}	$I_{S} = -1.0 \text{ A}$	-	-0.7	-1.2	V	
Body diode reverse recovery time	t _{rr}		-	32	50	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = -1.0 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	20	40	nC	
Reverse recovery fall time	t _a	$T_J = 25 ^{\circ}C$	-	16	-	ns ns	
Reverse recovery rise time	t _b		-	16	-	113	

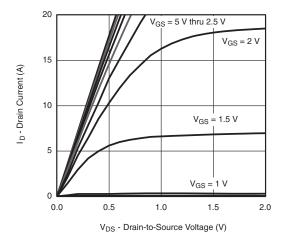
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

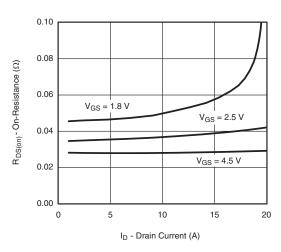
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



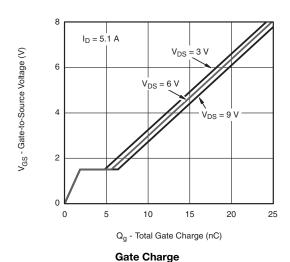
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

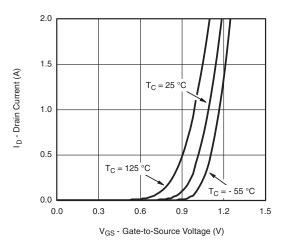


Output Characteristics

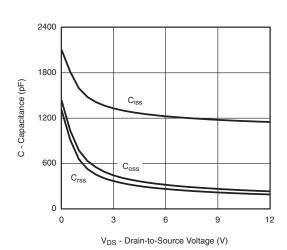


On-Resistance vs. Drain Current and Gate Voltage

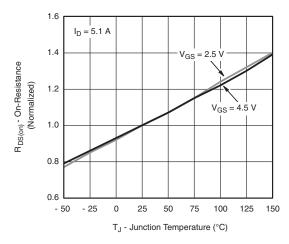




Transfer Characteristics



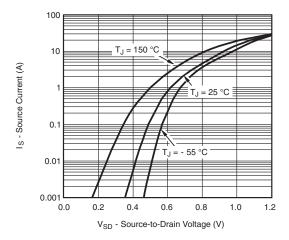
Capacitance



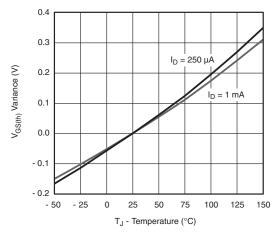
On-Resistance vs. Junction Temperature



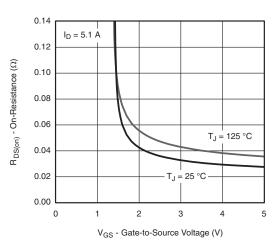
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



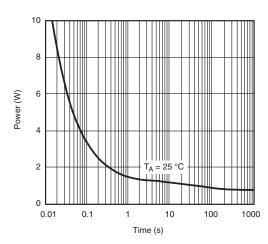
Source-Drain Diode Forward Voltage



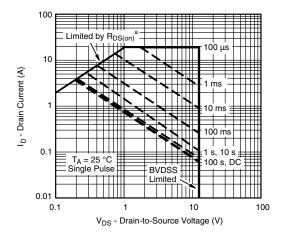
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage



Single Pulse Power



Safe Operating Area

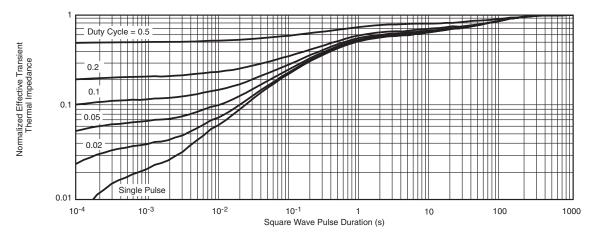
Note

a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

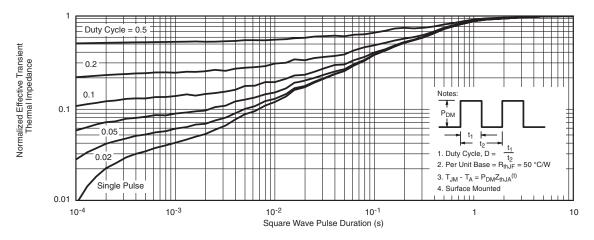
S20-0638-Rev. D, 24-Aug-2020



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



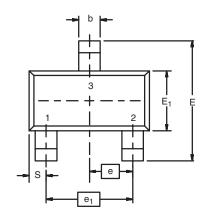
Normalized Thermal Transient Impedance, Junction-to-Foot

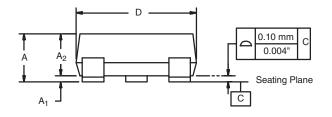
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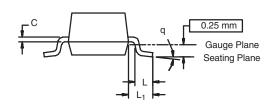
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SOT-23 (TO-236): 3-LEAD







Dim	MILLIN	IETERS	INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A ₁	0.01	0.10	0.0004	0.004	
A ₂	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E ₁	1.20	1.40	0.047	0.055	
е	0.95	BSC	0.037	4 Ref	
e ₁	1.90	BSC	0.074	8 Ref	
L	0.40	0.60	0.016	0.024	
L ₁	0.64 Ref		0.025	i Ref	
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	

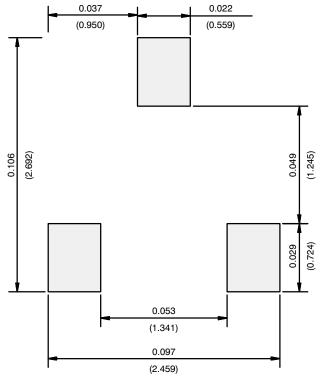
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RECOMMENDED MINIMUM PADS FOR SOT-23



Recommended Minimum Pads Dimensions in Inches/(mm)

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APPLICATION NOTE



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